

# **Product Change Notification - KSRA-14MRKE725**

#### Date:

09 May 2018

# **Product Category:**

8-bit PIC Microcontrollers; 16-Bit - Microcontrollers and Digital Signal Controllers

### **Affected CPNs:**

# **Notification subject:**

CCB 3028 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu)bond wire in selected products of the 0.25um TSMC wafer technology available in 44L QFN package at NSEB assembly

#### **Notification text:**

**PCN Status:** 

Final notification

**PCN Type:** 

Manufacturing Change

### **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

#### **Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 44L QFN package at NSEB assembly site.

#### Pre Change:

Using gold (Au) bond wire

#### **Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire

#### **Pre and Post Change Summary:**

	Pre Change	Post Change				
Assembly Site	NSEB Assembly Site	NSEB Assembly Site				
Wire material	Au Wire	CuPdAu Wire				
Die attach material	8600	8600				
Molding compound material	G700LTD	G700LTD				
Lead frame material	C194	C194				

#### Impacts to Data Sheet:

None

#### **Change Impact:**

None

#### **Reason for Change:**

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

#### **Change Implementation Status:**

In Progress

#### **Estimated First Ship Date:**

May 27, 2018 (date code: 1821)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and



post change parts.

### **Time Table Summary:**

	July 2017				April 2018			May 2018							
Workweek	26	27	28	29	30	->	14	15	16	17	18	19	20	21	22
Initial PCN Issue Date				Χ											
Qual Report Availability										Χ					
Final PCN Issue Date										Χ					
Estimated Implementation Date														X	

#### **Method to Identify Change:**

Traceability code

#### **Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan

## **Revision History:**

July 18, 2017: Issued initial notification.

**April 27, 2018:** Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on May 27, 2018.

May 09, 2018: Re-issued final notification to correct the attached gual report.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

# Attachment(s):

PCN\_KSRA-14MRKE725\_Qual\_report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

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To opt out of future offer or information emails (other than product change notification emails), click here to go to microchip DIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

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#### Affected Catalog Part Numbers (CPN)



PIC18F46J11T-I/ML

PIC18LF46J11-I/ML

PIC18LF46J11T-I/ML

PIC18F44J11-I/ML

PIC18F44J11T-I/ML

PIC18LF44J11-I/ML

PIC18LF44J11T-I/ML

PIC18F45J11-I/ML

PIC18F45J11T-I/ML

PIC18LF45J11-I/ML

PIC18LF45J11T-I/ML

PIC18F44J50-I/ML

PIC18F44J50T-I/ML

PIC18LF44J50-I/ML

PIC18LF44J50T-I/ML

PIC18F45J50-I/ML

PIC18F45J50T-I/ML

PIC18LF45J50-I/ML

PIC18LF45J50T-I/ML

PIC18F46J50-I/ML

PIC18F46J50T-I/ML

PIC18LF46J50-I/ML

PIC18LF46J50T-I/ML

PIC18F47J53-I/ML

PIC18F47J53T-I/ML

PIC18LF47J53-I/ML

PIC18LF47J53T-I/ML

PIC18F46J53-I/ML

PIC18F46J53T-I/ML

PIC18LF46J53-I/ML

PIC18LF46J53T-I/ML

PIC18F46J13-I/ML

PIC18F46J13T-I/ML

PIC18LF46J13-I/ML PIC18LF46J13T-I/ML

1101021 100101 1/1

PIC18F47J13-I/ML

PIC18F47J13T-I/ML

PIC18LF47J13-I/ML PIC18LF47J13T-I/ML

PIC24FJ32MC104-I/ML

DSPIC33FJ32GP104-I/ML

PIC24FJ64GA004-E/ML

PIC24FJ64GA004-I/ML

PIC24FJ64GA004-I/MLB4

PIC24FJ64GA004-I/MLC13

PIC24FJ64GA004T-I/ML

Date: Tuesday, May 08, 2018

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PIC24FJ32GA004-E/ML

PIC24FJ32GA004T-E/ML

PIC24FJ32GA004T-I/ML

PIC24FJ16GA004-E/ML

PIC24FJ16GA004-I/ML

PIC24FJ16GA004T-I/ML

PIC24FJ16GA004T-I/MLC09

PIC24FJ32GA004T-I/MLC12

PIC24FJ48GA004-E/ML

PIC24FJ48GA004-I/ML

PIC24FJ48GA004T-I/ML

PIC24FJ48GA004T-I/ML022

PIC24FJ64GA104-E/ML

PIC24FJ64GA104-I/ML

PIC24FJ64GA104T-E/ML

PIC24FJ64GA104T-I/ML

PIC24FJ32GA104-E/ML

PIC24FJ32GA104-I/ML

PIC24FJ32GA104-I/ML021

PIC24FJ32GA104-I/ML023

PIC24FJ32GA104-I/ML025

PIC24FJ32GA104T-E/ML

PIC24FJ32GA104T-I/ML

PIC24FJ32GA104T-I/ML021

PIC24FJ32GA104T-I/ML023

PIC24FJ32GA104T-I/ML024

PIC24FJ32GA104T-I/ML025

PIC24FJ64GB004-I/ML

PIC24FJ64GB004T-I/ML

PIC24FJ32GB004-I/ML

PIC24FJ32GB004T-I/ML

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